

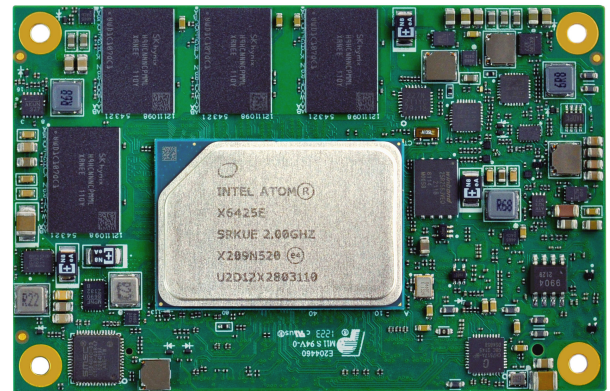
COM-X6425E

COM Express® Mini Size Type 10 Module with
Intel® Atom™ X6000E Processor System-on-Chip

产品功能

- ◆ 单,双, 四核 Intel® Atom™ X6000E SOC 处理器
- ◆ 板载 16GB DDR4 内存
- ◆ 板载 128-512G UFS 电子盘 (可以选择)
- ◆ 1 个双通道 18/24Bit LVDS 显示接口
- ◆ 2 个 RS232 接口
- ◆ 1 个 CRT 和 HDMI 显示接口
- ◆ 3 个 PCIe x1, 1 个 2.5G GbE
- ◆ 2 个 SATA , 4 个 USB3.0
- ◆ 2 个 2.5G TSN 网络
- ◆ 工作温度: -25°C to +75°C

扩展温度: -40°C to +85°C



技术参数

核心系统

CPU	Single, dual, quad-core Intel® Atom™ X6000E X6425E 2.0 GHz (3.0GHz 12W (4C)) X6413E 1.5 GHz (3.0GHz 9W (4C)) X6211E 1.3 GHz (3.0GHz 6W (2C)) X6200FE 1.0 GHz (3.0GHz 4.5W (2C)) no GPU
Memory	DDR4, memory up to 16GB
Embedded BIOS	AMI EFI with CMOS backup in 8MB SPI BIOS
Cache	TBC
Expansion Bussess	3 PCI Express x1 Gen2 (AB): lanes 0/1/2; Optional PCIe x4 (lose GbE) LPC bus, SMBus (system), I ² C (user)

显示

GPU Feature	11th Intel® graphics Core architecture
Display Interface LVDS/eDP /CRT	One DDI channel supporting DisplayPort/HDMI/DVI Double channel 18/24-bit LVDS eDP support(optional) CRT support

声卡

Chipset	Intel® HD Audio integrated in SOC
Audio Codec	Located on carrier COM-E3845-X 底板

网络

Intel® MAC/PHY Interface	Intel® i225 (MAC/PHY) Ethernet controller 100M/1000M/2.5G GbE connection
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I/O 接口

USB	2xUSB 3.0 4x USB 2.0
SATA	2 SATA
Serial	2 UART
eMMC	32G to 256 GB
GPIO	4 GPO and 4 GPI

扩展 I/O

Standard Input	On carrier if needed (standard support for SMC3114)
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电源

Standard Input	ATX = 12V±2% / 5Vsb ±5% or AT = 12V±2%
Wide Input	ATX = 5-20V / 5Vsb (standard temp. only) ATX = 5-20V / 5Vsb (standard temp. only)
Management	ACPI 4.0 compliant, Smart Battery support
Power States	C0, C1, C1E, C4, C6 S0, S3, S4, S5 (Wake on USB S3/S4, WOL S3/S4/S5)
ECO mode	Supports deep S5 (ECO mode) for power saving

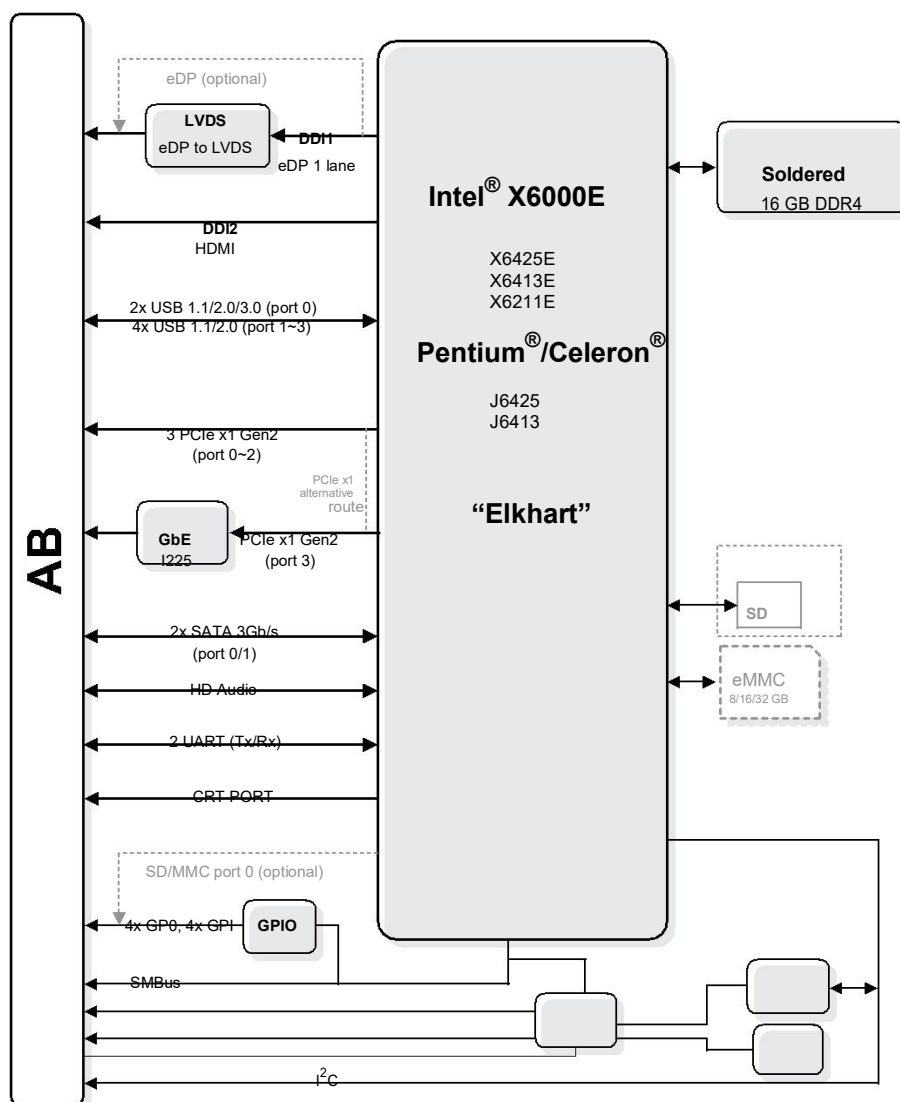
机械尺寸及环境

Form Factor	PICMG COM.0: Rev 2.1 Type 10
Dimension	Mini size: 84 mm x 55 mm
Operating Temperature	Standard: -25°C to +75°C Extreme Rugged: -40 to +85°C
Humidity	5-90% RH operating, non-condensing 5-95% RH storage (operating with conformal coating) MIL-STD-202F, Method 213B, Table 213H, Condition A and Method 214A, Table 214-I Condition D
HALT	Thermal Stress, Vibration Stress, Thermal Shock and Combined Test

操作系统支持

Standard Support	Win10/64-bit, Win10 IOT 64-bit, Yocto Linux 64-bit VxWorks 64-bit, Ubuntu (TPC)
Extended Support	Yocto project based Linux 64-bit

功能框图



订购信息

COM Express 模块

模块型号	产品描述及设置
COM-X6425E	X6425E CPU/2.0GHz /16GB DDR4
COM-X6413E	X6413E CPU/1.5GHz /16GB DDR4
COM-X6211E	X6411E CPU/1.3GHz /16GB DDR4
COM-X6200FE	X6200FE CPU/1.0GHz /16GB DDR4/NO GPU

开发工具

模块型号	产品描述及设置
COM	Express Type10 开发底板
COM	COM-X6425E 核心主板
电子盘	mSATA-32G 电子盘
配件	电缆, 散热器, 螺柱